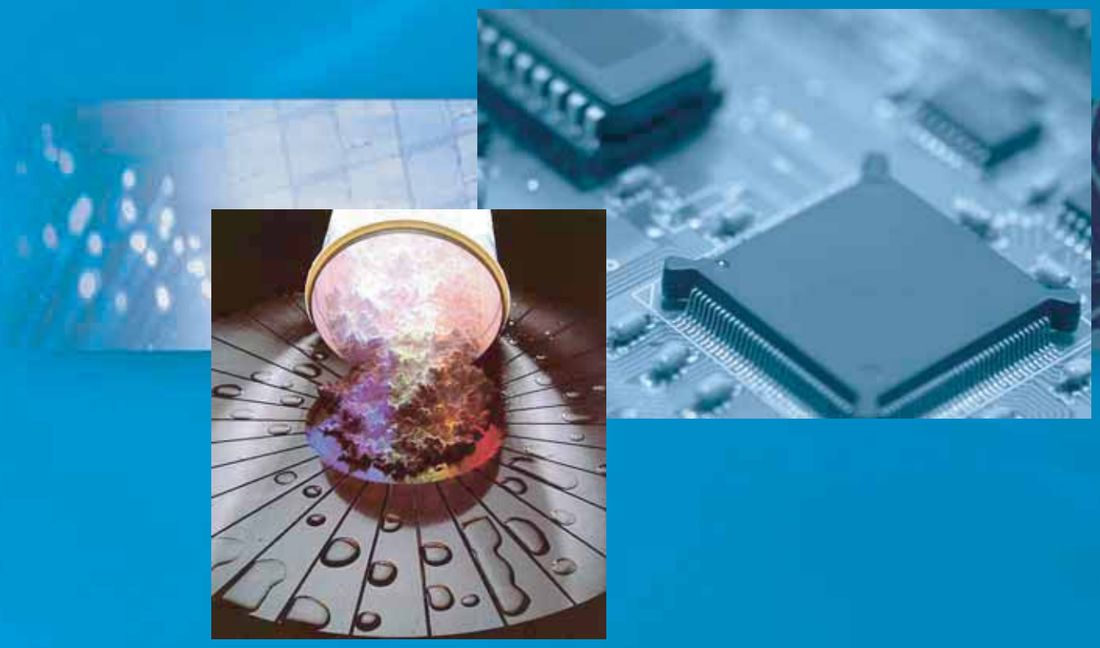
Bni62

Bni62 Feature

Unit size :	800(W)x800(D)x1400(H)mm (including cover)
Rotation of plate :	1-150rpm
Diameter of plate :	500mm
Applied Jig :	up to 6 inch jig
Sweep arm :	2 arms (standard)
Slurry feeding :	auto mixing and feeding
Timer :	Max. 99Hour 59Minutes
Operation :	Touch panel control
Net weight:	250kg (including cover)
Power Supply:	100V/240V
Consumption current:	25A/10A

Precision Materials Processing



BN TECHNOLOGY CORPORATION
A MEMBER OF BN INTERNATIONAL GROUP

BN Technology Corporation

Head office
Level 5, Pacific Marks Shinjuku Parkside
4-15-7 Nishi-Shinjuku, Shinjuku-ku, Tokyo 160-0023, Japan
TEL: +81-3-5365-2551 FAX: +81-3-5365-3900
E-mail: info@bn-technology.co.jp
URL: www.bn-technology.co.jp

Technical center
3-1-2 Osawa, Mitakashi, Tokyo 181-0015, Japan
TEL: +81-42-230-5440 FAX: +81-42-230-5441

Extreme precise Lapping/Polishing Machine

Achieve extreme precise polishing under nano-technology environment

Bni62 System feature

Optimum system
Offer not only hardware but also optimum system as package including technology and know-how up to 6" wafer.

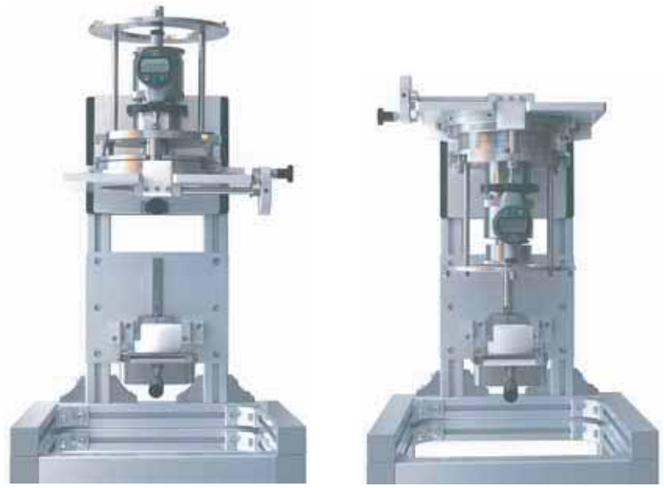
Capability for research laboratories up to small volume production
Bni62 covers extreme precise lapping and polishing with itself and can be used for research laboratories up to small volume production.

Extreme precise Polishing machine to quest for perfect repeatability
Control polishing condition and slurry with high accuracy and guarantee better polishing repeatability.

Chemical resistance (resistant to Alkali & Acid)
Resistant to chemical with the surface to be exposed to slurry is coated with Teflon, polishing jig is made of stainless steel.

Research, Development, Small volume Production!!!

Max 6" Jig x 2 Sweep stage as standard
Equipped with the cover for Clean room



Polishing Jig, Instrument to reverse a Jig
Hold the work firmly and control the process. Can be customized by user's request and apply for various applications. Prepare a instrument to reverse a jig as standard to keep safety with handling the heavy jig.

Application

Leading edge semiconductor crystal material
Piled up many achievements at lapping and polishing Si wafer by CMP, compound semiconductor like GaN, GaAs etc., hard substrate material like SiC etc., and various optical materials.

At Si wafer CMP, not only simple planarization, but wafer size delayering, extreme precise polishing with multiplayer of Oxide like SiO2 etc., Nitride like SiN etc., various material coating that covers crystal and sapphire substrate of optics can be performed.

Achieve the essential quality level for epitaxial growth after extreme precise polishing to achieve sub-nano level surface roughness. Achieve not only thinning of Si wafer, but thinning bonded semiconductors, optical material and compound semiconductors with extreme precise polishing.

- Si wafer CMP
  (Delayering and Planarization)
- Hard substrate for semiconductor, Sapphire, GaN, SiC etc.
- Compound semiconductor GaAs etc.
- Substrate corrective polishing before epitaxial growth
- Multi-player of Oxide like SiO_2 etc., Nitride like SiN etc.
- R&D for CMP process, slurry, pad
- Various optical material that is coated on various substrate

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Precise CMP
Offer most suitable machine to achieve requested surface flatness and uniformity of thickness.

Lapping /Polishing
Achieve best surface roughness with unique and precise jig and plate under the background of advanced technology of Chemical Mechanical Polishing (CMP) etc.

Polishing slurry
Offer optimum solution that is suitable to user' s application with various polishing materials, lapping powder to CMP slurry.

Polishing plate
Offer optimum polishing plate that is suitable for user's work and object.

Provide various plate.
- Cast iron
- Tin
- Plate for polishing cloth
- Glass
- Polyurethane

Provide optimum plate, other material, trench that is requested from users.